

NZX series

Single Zener diodes Rev. 02 — 3 June 2009

Product data sheet

Product profile

1.1 General description

General-purpose Zener diodes in a SOD27 (SC-40) small hermetically sealed glass package.

1.2 Features

- Total power dissipation: P_{tot} ≤ 500 mW
- Low differential resistance
- Low leakage current
- AEC-Q101 qualified

1.3 Applications

General regulation functions

1.4 Quick reference data

Quick reference data Table 1.

 $T_i = 25 \,^{\circ}C$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{F}	forward voltage	$I_F = 200 \text{ mA}$	<u>[1]</u> -	-	1.5	V

^[1] Pulse test: $t_p \le 300 \ \mu s; \ \delta \le 0.02.$

Pinning information 2.

		_	_	_
Tabl	e 2	P	inn	ina

	•		
Pin	Description	Simplified outline	Graphic symbol
1	cathode	[1]	
2	anode	k a	122

^[1] The marking band indicates the cathode.



3. Ordering information

Table 3. Ordering information

Type number	Package							
	Name	Description	Version					
NZX2V4A to NZX36X ^[1]	SC-40	hermetically sealed glass package; axial leaded; 2 leads	SOD27					

^[1] The series consists of 111 types with nominal working voltages from 2.4 V to 36 V.

4. Marking

Table 4. Marking codes

Type number	Marking code
NZX2V4A to NZX36X	the diodes are type branded

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
I_{F}	forward current		-	250	mA
P _{tot}	total power dissipation	$T_{tp} \le 25 ^{\circ}C$	-	500	mW
T _j	junction temperature		-	175	°C
T_{amb}	ambient temperature		– 55	+175	°C
T _{stg}	storage temperature		-65	+175	°C

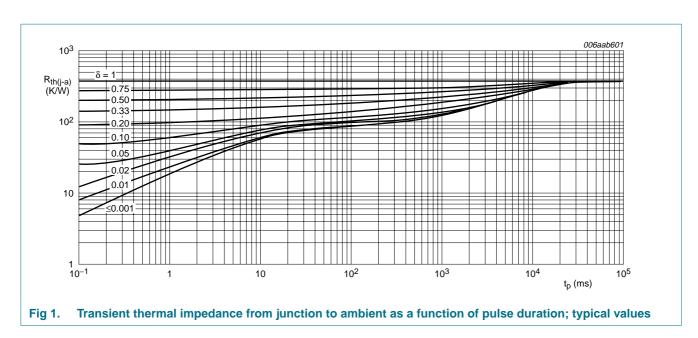
6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	<u>[1]</u>	-	-	380	K/W
$R_{th(j-t)}$	thermal resistance from junction to tie-point		<u>[1]</u>	-	-	300	K/W

^[1] Device mounted on an FR4 Printed-Circuit Board (PCB) without metallization pad; maximum lead length 8 mm.

NZX_SER_2 © NXP B.V. 2009. All rights reserved.



7. Characteristics

Table 7. Characteristics

 $T_i = 25 \,^{\circ}C$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{F}	forward voltage	$I_F = 200 \text{ mA}$	<u>[1]</u> -	-	1.5	V

^[1] Pulse test: $t_p \le 300~\mu s;~\delta \le 0.02.$

Table 8. Characteristics per type; NZX2V4A to NZX18C

 $T_i = 25$ °C unless otherwise specified.

NZXxxx	Sel	Working vo V _Z (V)	ltage	Differential resistance r _{dif} (Ω)	Reverse current I _R (μA)	
		I _Z = 5 mA		I _Z = 5 mA		
		Min	Max	Max	Max	V _R (V)
2V4	Α	2.3	2.5	100	50	1
	В	2.4	2.6			
2V7	Α	2.5	2.7	100	20	1
	В	2.6	2.8			
	С	2.7	2.9			
3V0	Α	2.8	3.0	100	10	1
	В	2.9	3.1			
	С	3.0	3.2			
3V3	Α	3.1	3.3	100	5	1
	В	3.2	3.4			
	С	3.3	3.5			

Table 8. Characteristics per type; NZX2V4A to NZX18C ...continued $T_j = 25 \,^{\circ}$ C unless otherwise specified.

NZXxxx Sel		Working V _Z (V)	voltage	Differential resistance r_{dif} (Ω)	Reverse current I _R (μA)	
		$I_Z = 5 \text{ m/s}$	4	$I_Z = 5 \text{ mA}$		
		Min	Max	Max	Max	V _R (V)
3V6	Α	3.4	3.6	100	5	1
	В	3.5	3.7			
	С	3.6	3.8			
3V9	Α	3.7	3.9	100	3	1
	В	3.8	4.0			
	С	3.9	4.1			
4V3	Α	4.0	4.2	100	3	1
	В	4.1	4.3			
	С	4.2	4.4			
	D	4.3	4.5			
4V7	Α	4.4	4.6	100	3	2
	В	4.5	4.7			
	С	4.6	4.8			
	D	4.7	4.9			
5V1	Α	4.8	5.0	100	2	2
	В	4.9	5.1			
	С	5.0	5.2			
	D	5.1	5.3			
5V6	Α	5.2	5.5	40	1	2
	В	5.3	5.6			
	С	5.4	5.7			
	D	5.5	5.8			
	Е	5.6	5.9			
6V2	Α	5.7	6.0	15	3	4
	В	5.8	6.1			
	С	6.0	6.3			
	D	6.1	6.4			
	Е	6.3	6.6			
6V8	Α	6.4	6.7	15	2	4
	В	6.6	6.9			
	С	6.7	7.0			
	D	6.9	7.2			

5 of 12

Table 8. Characteristics per type; NZX2V4A to NZX18C ...continued $T_j = 25 \,^{\circ}$ C unless otherwise specified.

NZXxxx	Sel	Working V _Z (V)	voltage	Differential resistance $r_{dif}(\Omega)$	Reverse (μA)	current
		I _Z = 5 mA		I _Z = 5 mA		
		Min	Max	Max	Max	V _R (V)
7V5 A	Α	7.0	7.3	15	1	5
	В	7.2	7.6			
	С	7.3	7.7			
	D	7.5	7.9			
	X	7.07	7.45			
8V2	Α	7.7	8.1	20	0.7	5
	В	7.9	8.3			
	С	8.1	8.5			
	D	8.3	8.7			
9V1	Α	8.5	8.9	20	0.5	6
	В	8.7	9.1			
	С	8.9	9.3			
	D	9.1	9.5			
	Е	9.3	9.7			
10	Α	9.5	9.9	25	0.2	7
	В	9.7	10.1			
	С	9.9	10.3			
	D	10.2	10.6			
11	Α	10.4	10.8	25	0.1	8
	В	10.7	11.1			
	С	10.9	11.3			
	D	11.1	11.6			
12	Α	11.4	11.9	35	0.1	8
	В	11.6	12.1			
	С	11.9	12.4			
	D	12.2	12.7			
	X	11.44	12.03			
13	Α	12.4	12.9	35	0.1	8
	В	12.6	13.1			
	С	12.9	13.4			
14	Α	13.2	13.7	35	0.05	9.8
	В	13.5	14.0			
	С	13.8	14.3			

Table 8. Characteristics per type; NZX2V4A to NZX18C ...continued $T_j = 25 \,^{\circ}$ C unless otherwise specified.

NZXxxx	Sel	Working V _Z (V)	voltage	Differential resistance $r_{dif}(\Omega)$	Reverse current I_R (μ A)		
		$I_Z = 5 \text{ mA}$	1	$I_Z = 5 \text{ mA}$			
		Min	Max	Max	Max	V _R (V)	
15	Α	14.1	14.7	40	0.05	10.5	
	В	14.5	15.1				
	С	14.9	15.5				
	X	14.35	15.09				
16	Α	15.3	15.9	45	0.05	11.2	
	В	15.7	16.5				
	С	16.3	17.1				
18	Α	16.9	17.7	55	0.05	12.6	
	В	17.5	18.3				
	С	18.1	19.0				

Table 9. Characteristics per type; NZX20A to NZX36X

 $T_j = 25 \,^{\circ}C$ unless otherwise specified.

NZXxxx	Sel	Working voltage V _Z (V)		Differential resistance $r_{dif}(\Omega)$	Reverse current I _R (μA)	
		I _Z = 2 mA		I _Z = 2 mA		
		Min	Max	Max	Max	V _R (V)
20	Α	18.8	19.7	60	0.05	14
	В	19.5	20.4			
	С	20.2	21.2			
22	Α	20.9	21.9	65	0.05	15.4
	В	21.6	22.6			
	С	22.3	23.3			
24	Α	22.9	24.0	70	0.05	16.8
	В	23.6	24.7			
	С	24.3	25.5			
	Χ	22.61	23.77			
27	Α	25.2	26.6	80	0.05	18.9
	В	26.2	27.6			
	С	27.2	28.6			
	Χ	26.99	28.39			
30	Α	28.2	29.6	100	0.05	21
	В	29.2	30.6			
	С	30.2	31.6			
	Χ	29.02	30.51			
33	Α	31.2	32.6	120	0.05	23.1
	В	32.2	33.6			
	С	33.2	34.5			
36	Α	34.2	35.7	140	0.05	25.2
	В	35.3	36.8			
	С	36.4	38.0			
	Χ	35.36	37.19			

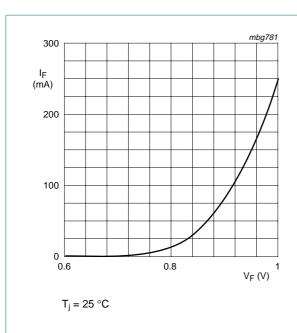
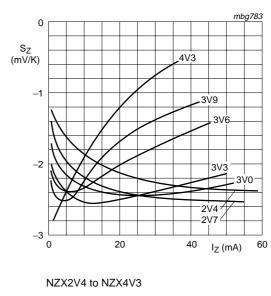
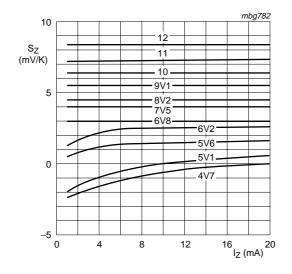


Fig 2. Forward current as a function of forward voltage; typical values



 $T_i = 25 \,^{\circ}\text{C}$ to 150 $^{\circ}\text{C}$

Fig 3. Temperature coefficient as a function of working current; typical values



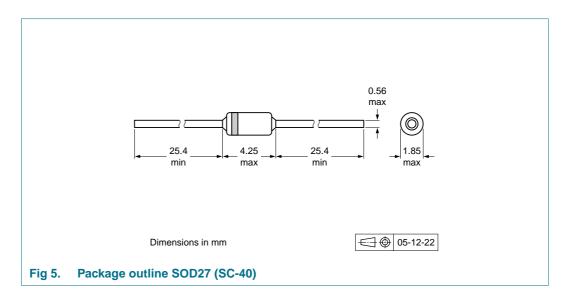
NZX4V7 to NZX12

 $T_i = 25 \,^{\circ}\text{C}$ to 150 $^{\circ}\text{C}$

Temperature coefficient as a function of working current; typical values Fig 4.

NZX_SER_2 © NXP B.V. 2009. All rights reserved.

8. Package outline



9. Packing information

Table 10. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number[2]	Package	Description	Packing	Packing quantity	
			5000	10000	
NZX2V4A to NZX36X	SOD27	26 mm tape ammopack, axial	-143	-	
		52 mm tape ammopack, axial	-	-133	
		52 mm reel pack, axial	-	-113	

^[1] For further information and the availability of packing methods, see Section 12.

^[2] The series consists of 111 types with nominal working voltages from 2.4 V to 36 V.



10. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
NZX_SER_2	20090603	Product data sheet	-	NZX_SER_1
Modifications:	 42 type numbers added Section 1.1 "General description": amended Figure 1: updated Table 5: Ptot condition amended 			
NZX_SER_1	20080724	Product data sheet	-	-

11. Legal information

11.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

11.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

11.3 Disclaimers

General — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental

damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

Terms and conditions of sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at http://www.nxp.com/profile/terms, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by NXP Semiconductors. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from national authorities.

Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

11.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

12. Contact information

For more information, please visit: http://www.nxp.com

For sales office addresses, please send an email to: salesaddresses@nxp.com

NZX_SER_2 © NXP B.V. 2009. All rights reserved.



13. Contents

1	Product profile
1.1	General description
1.2	Features
1.3	Applications
1.4	Quick reference data
2	Pinning information 1
3	Ordering information 2
4	Marking 2
5	Limiting values 2
6	Thermal characteristics 2
7	Characteristics 3
8	Package outline 9
9	Packing information 9
10	Revision history
11	Legal information
11.1	Data sheet status
11.2	Definitions
11.3	Disclaimers
11.4	Trademarks 11
12	Contact information
13	Contents 12

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

